

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED


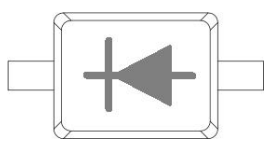
MMSZ5221B-MMSZ5259B

Product specification

FEATURES

- Planar Die Construction
- Ultra-Small Surface Mount Package
- General purpose, Medium Current
- Ideally Suited for Automated Assembly Processes

Reference News

PACKAGE OUTLINE	PIN CONFIGURATION
	
SOD-123	

Maximum Ratings(Ta=25 °C unless otherwise specified)

Characteristic	Symbol	Value	Unit
Forward Voltage (Note 2) @ I _F = 10mA	V _F	0.9	V
Power Dissipation(Note 1)	P _d	500	mW
Thermal Resistance, Junction to Ambient Air	R _{θJA}	357	°C/W
Operation Junction and Storage Temperature Range	T _J , T _{stg}	-55~+150	°C

Notes:1. Device mounted on ceramic PCB; 7.6 mm x 9.4 mm x 0.87 mm with pad areas 25 mm².

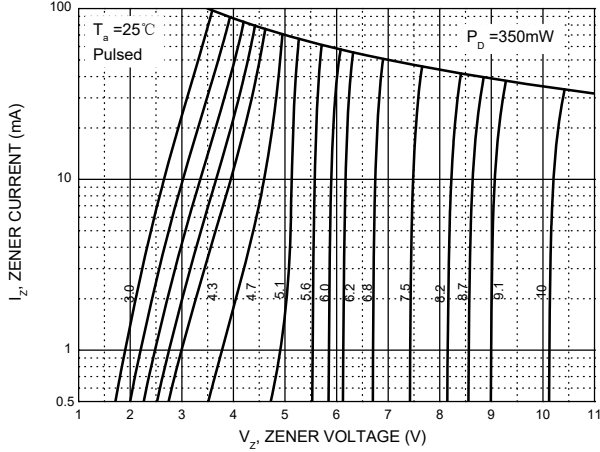
2. Tested with pulses, T_p ≤ 1.0ms.

ELECTRICAL CHARACTERISTICS

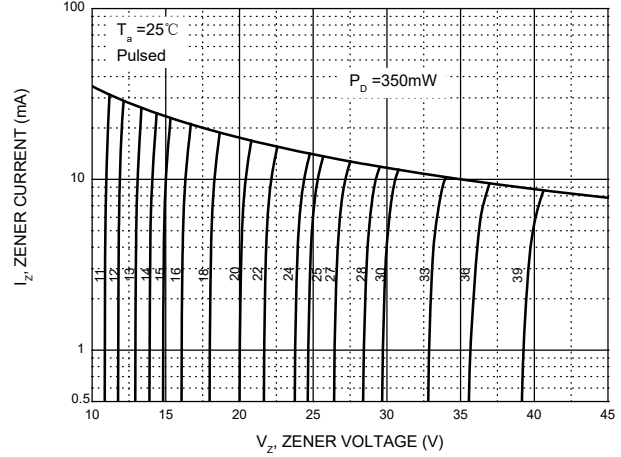
 T_a=25°C unless otherwise specified

Type Number	Code	Zener Voltage Range (Note 2)				Maximum Zener Impedance (Note 4)			Maximum Reverse Current	
		V _Z @ I _{ZT}			I _{ZT}	Z _{ZT} @ I _{ZT}	Z _{ZK} @ I _{ZK}	I _{ZK}	I _R	V _R
		Nom(V)	Min(V)	Max(V)	mA	Ω		mA	uA	V
MMSZ5221B	C1	2.4	2.28	2.52	20	30	1200	0.25	100	1.0
MMSZ5223B	C3	2.7	2.57	2.84	20	30	1300	0.25	75	1.0
MMSZ5225B	C5	3.0	2.85	3.15	20	30	1600	0.25	50	1.0
MMSZ5226B	G1	3.3	3.14	3.47	20	28	1600	0.25	25	1.0
MMSZ5227B	G2	3.6	3.42	3.78	20	24	1700	0.25	15	1.0
MMSZ5228B	G3	3.9	3.71	4.10	20	23	1900	0.25	10	1.0
MMSZ5229B	G4	4.3	4.09	4.52	20	22	2000	0.25	5	1.0
MMSZ5230B	G5	4.7	4.47	4.94	20	19	1900	0.25	5	2.0
MMSZ5231B	E1	5.1	4.85	5.36	20	17	1600	0.25	5	2.0
MMSZ5232B	E2	5.6	5.32	5.88	20	11	1600	0.25	5	3.0
MMSZ5233B	E3	6.0	5.70	6.30	20	7	1600	0.25	5	3.5
MMSZ5234B	E4	6.2	5.89	6.51	20	7	1000	0.25	5	4.0
MMSZ5235B	E5	6.8	6.46	7.14	20	5	750	0.25	3	5.0
MMSZ5236B	F1	7.5	7.13	7.88	20	6	500	0.25	3	6.0
MMSZ5237B	F2	8.2	7.79	8.61	20	8	500	0.25	3	6.5
MMSZ5238B	F3	8.7	8.27	9.14	20	8	600	0.25	3	6.5
MMSZ5239B	F4	9.1	8.65	9.56	20	10	600	0.25	3	7.0
MMSZ5240B	F5	10	9.50	10.50	20	17	600	0.25	3	8.0
MMSZ5241B	H1	11	10.45	11.55	20	22	600	0.25	2.0	8.4
MMSZ5242B	H2	12	11.40	12.60	20	30	600	0.25	1.0	9.1
MMSZ5243B	H3	13	12.35	13.65	9.5	13	600	0.25	0.5	9.9
MMSZ5244B	H4	14	13.30	14.70	9.0	15	600	0.25	0.1	10
MMSZ5245B	H5	15	14.25	15.75	8.5	16	600	0.25	0.1	11
MMSZ5246B	J1	16	15.20	16.80	7.8	17	600	0.25	0.1	12
MMSZ5248B	J3	18	17.10	18.90	7.0	21	600	0.25	0.1	14
MMSZ5250B	J5	20	19.00	21.00	6.2	25	600	0.25	0.1	15
MMSZ5251B	K1	22	20.90	23.10	5.6	29	600	0.25	0.1	17
MMSZ5252B	K2	24	22.80	25.20	5.2	33	600	0.25	0.1	18
MMSZ5253B	K3	25	23.75	26.25	5.0	35	600	0.25	0.1	19
MMSZ5254B	K4	27	25.65	28.35	5.0	41	600	0.25	0.1	21
MMSZ5255B	K5	28	26.60	29.40	4.5	44	600	0.25	0.1	21
MMSZ5256B	M1	30	28.50	31.50	4.2	49	600	0.25	0.1	23
MMSZ5257B	M2	33	31.35	34.65	3.8	58	700	0.25	0.1	25
MMSZ5258B	M3	36	34.20	37.80	3.4	70	700	0.25	0.1	27
MMSZ5259B	M4	39	37.05	40.95	3.2	80	800	0.25	0.1	30
MMSZ5266B	P1	68	64.6	71.4	1.8	230	1600	0.25	0.1	52

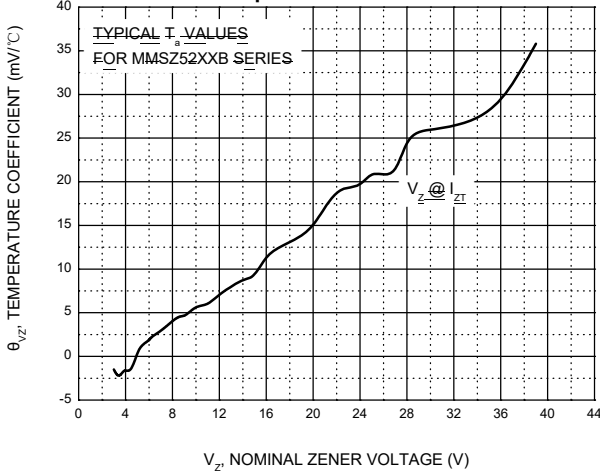
Zener Characteristics (V_z Up to 10 V)



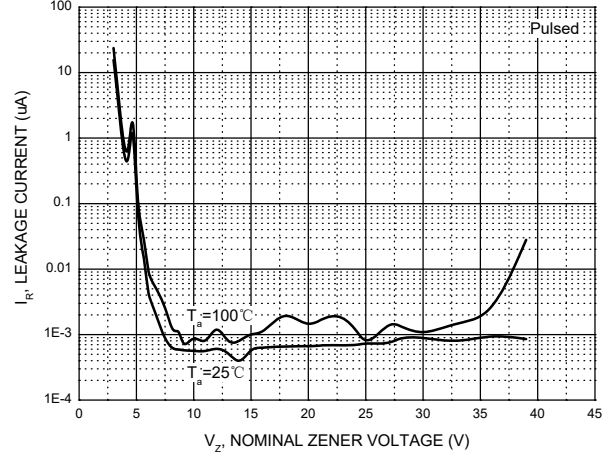
Zener Characteristics (11 V to 39 V)



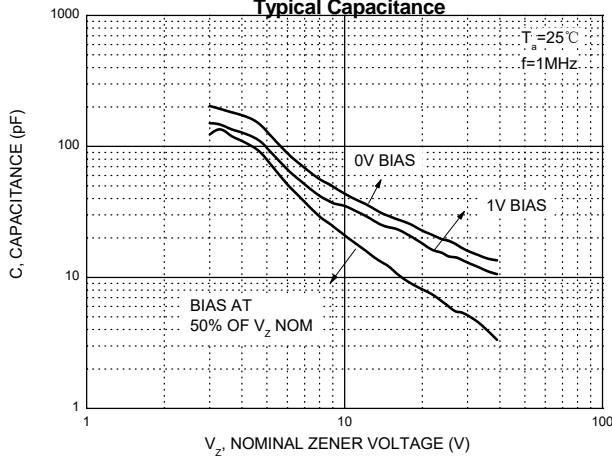
Temperature Coefficients



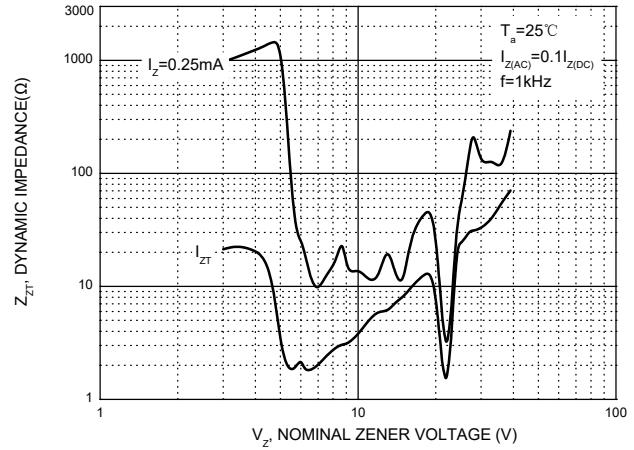
Typical Leakage Current



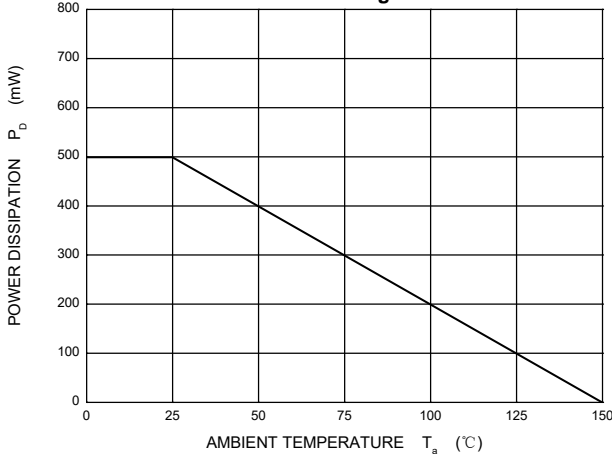
Typical Capacitance



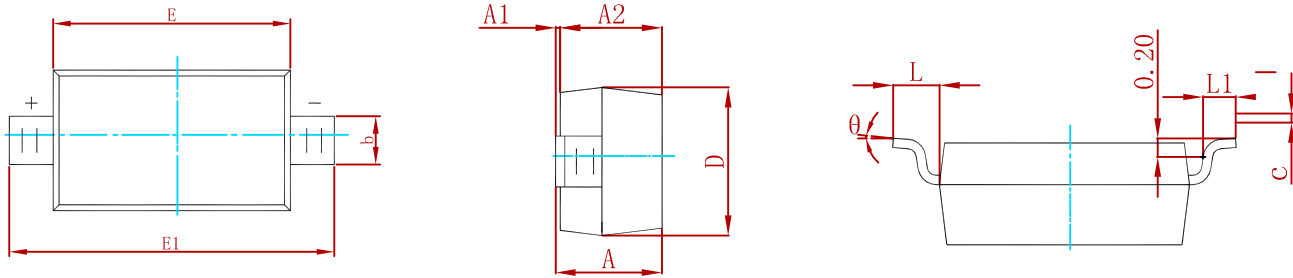
Effect of Zener Voltage on Zener Impedance



Power Derating Curve

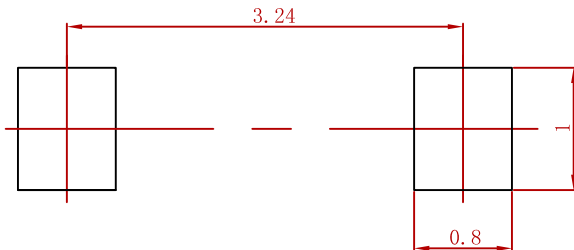


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.450	0.650	0.018	0.026
c	0.080	0.150	0.003	0.006
D	1.500	1.700	0.059	0.067
E	2.600	2.800	0.102	0.110
E1	3.550	3.850	0.140	0.152
L	0.500 REF		0.020 REF	
L1	0.250	0.450	0.010	0.018
θ	0°	8°	0°	8°

Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MMSZ5221B-MMSZ5259B	SOD-123	3000

Attention

- Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.
- MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MSKSEMI Semiconductor products described or contained herein.
- Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- MSKSEMI Semiconductor strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all MSKSEMI Semiconductor products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.
- Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringement of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the MSKSEMI Semiconductor product that you intend to use.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for [Zener Diodes](#) category:

Click to view products by [MSKSEMI](#) manufacturer:

Other Similar products are found below :

[RKZ13B2KG#P1](#) [DL5234B](#) [EDZTE6113B](#) [1N4682](#) [1N4693](#) [1N4732A](#) [1N4736A](#) [1N4750A](#) [1N4759ARL](#) [1N5241B](#) [1N5365B](#) [1N5369B](#)
[1N747A](#) [1N964B](#) [1N966B](#) [1N968B](#) [1N972B](#) [JANS1N4974US](#) [JANTX1N5907](#) [1N4692](#) [1N4700](#) [1N4702](#) [1N4704](#) [1N4711](#) [1N4714](#)
[1N4745ARL](#) [1N4752ARL](#) [1N4760ARL](#) [1N5221B](#) [1N5242BTR](#) [1N5350B](#) [1N5352B](#) [1N961BRR1](#) [1N964BRL](#) [RKZ5.1BKU#P6](#)
[3SMAJ5946B-TP](#) [3SMAJ5950B-TP](#) [3SMBJ5925B-TP](#) [MMSZ5230BQ-13-F](#) [MMSZ5232BQ-13-F](#) [BZX84C7V5](#) [3SMAJ5945B-TP](#)
[3SMAJ5947B-TP](#) [3SMBJ5941B-TP](#) [DL4732A-T3](#) [DZ2S240M0L](#) [SMAZ27-TP](#) [ZMM5224B-7](#) [RD16UM-T1-A](#) [RD39S-T1-A](#)